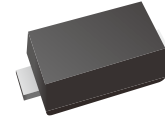


Surface Mount Schottky Barrier Rectifier

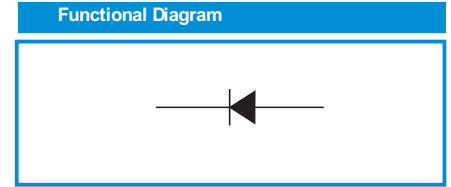
Reverse Voltage - 20V~60V

Forward Current - 1.0A



Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



Mechanical Data

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz
- Polarity: Color band denotes cathode end

Absolute Maximum Ratings and Electiral characteristics

Parameter	Symbols	LT1F20	LT1F40	LT1F60	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	V
Maximum RMS voltage	V_{RMS}	14	28	42	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	30			A
Max Instantaneous Forward Voltage at 1 A	V_F	0.45		0.50	V
Maximum DC Reverse Current $T_a = 25^{\circ}C$ at Rated DC Reverse Voltage $T_a = 100^{\circ}C$	I_R	0.3 10	0.2 5		mA
Typical Junction Capacitance ⁽¹⁾	C_j	180		80	pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	85			$^{\circ}C/W$
Operating Junction Temperature Range	T_j	-55 ~ +125			$^{\circ}C$
Storage Temperature Range	T_{stg}	-55 ~ +150			$^{\circ}C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Characteristics Curves

Fig.1 Forward Current Derating Curve

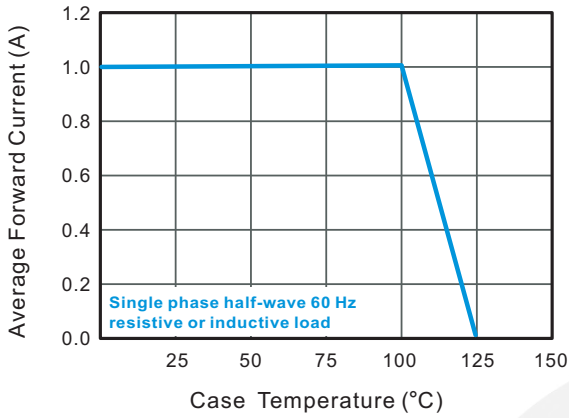


Fig.2 Typical Reverse Characteristics

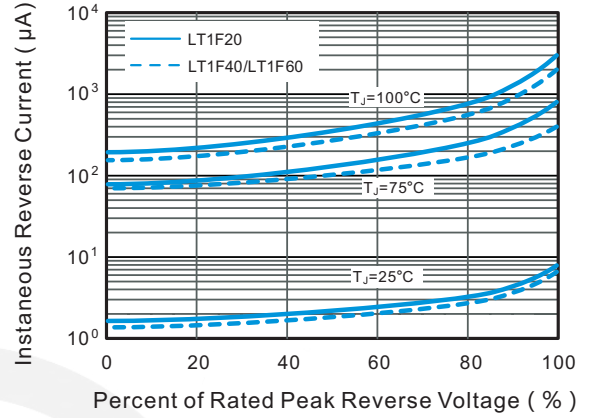


Fig.3 Typical Forward Characteristic

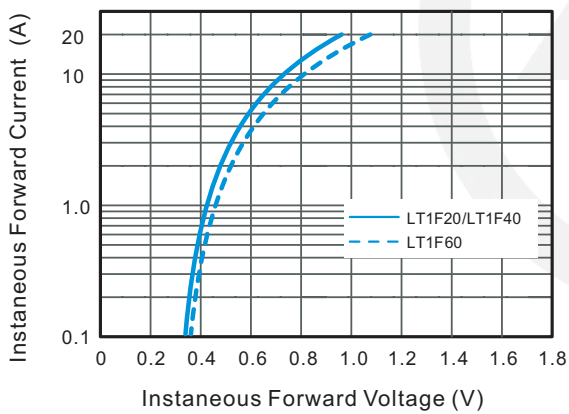


Fig.4 Typical Junction Capacitance

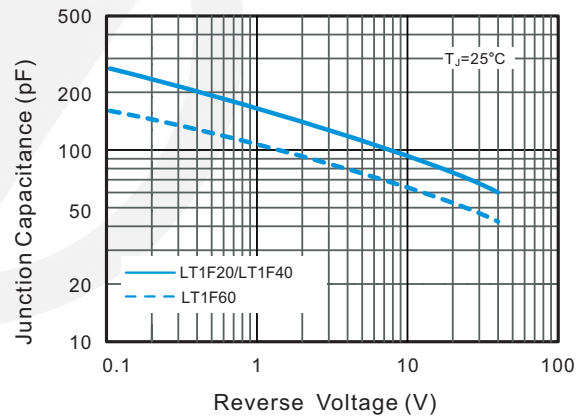


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

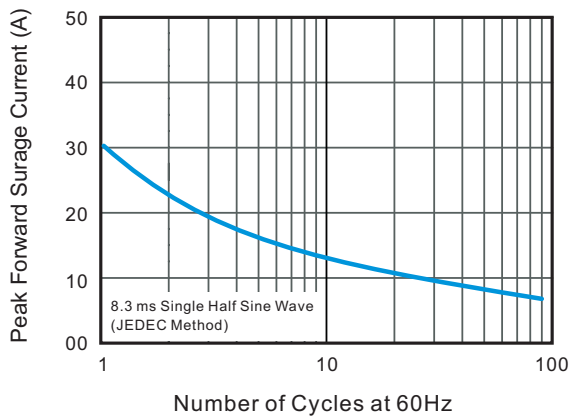
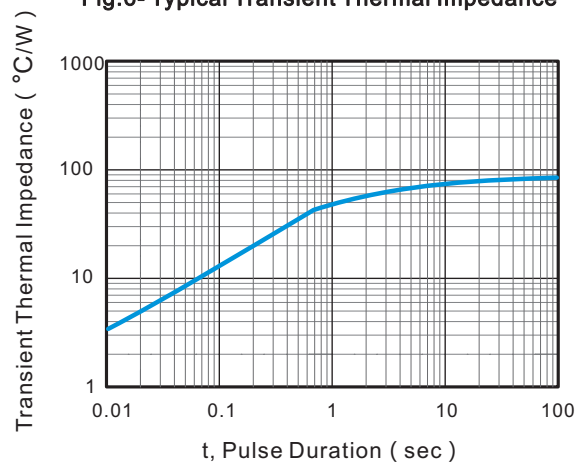
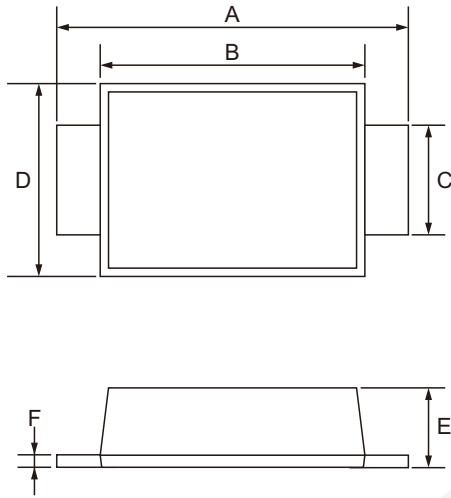


Fig.6- Typical Transient Thermal Impedance

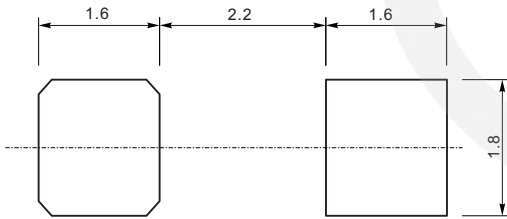


SMAF Package Outline



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	4.40	4.90
B	3.30	3.70
C	1.30	1.60
D	2.40	2.70
E	0.90	1.20
F	0.12	0.20

SMAF Suggested Pad Layout

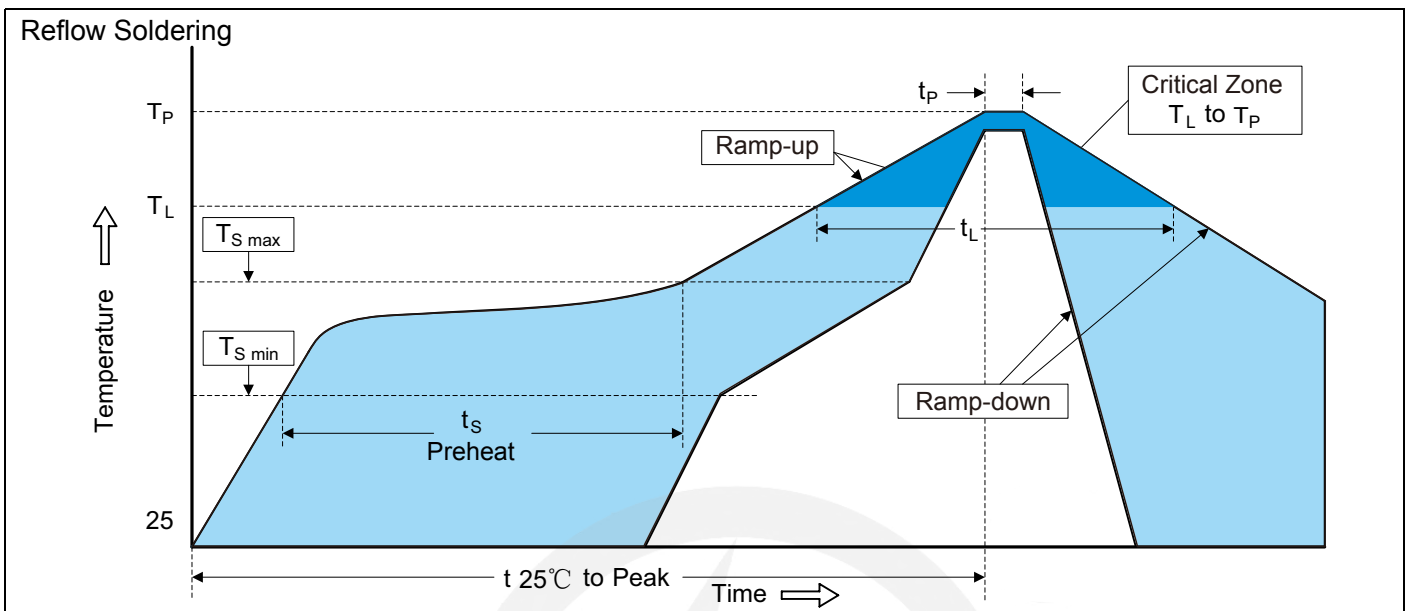


Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$
 3. The pad layout is for reference purpose only.

Marking

Type number	Marking code
LT1F20	SSL12
LT1F40	SSL14
LT1F60	SSL16

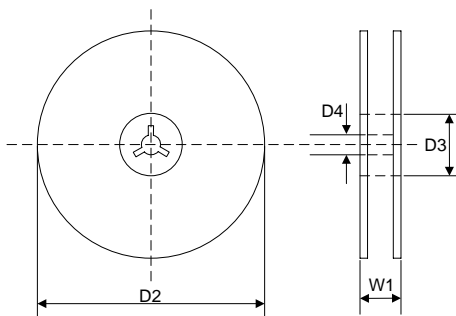
Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat -Temperature Min (T _{S min}) -Temperature Max (T _{S max}) -Time (min to max) (t _s)	150°C 200°C 60-180 seconds
T _{S max} to T _L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T _L) -Time (t _L)	217°C 60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

7" Reel



D2 Φ178.0±2.0

D3 Φ50.0Min.

D4 Φ13.0±0.5

W1 16.0±2.0

Quantity: 3000PCS